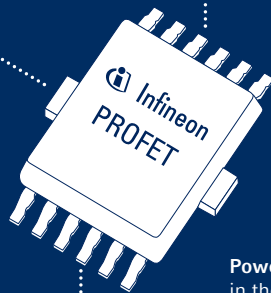


Automotive & Industrial

Dr. Reinhard Ploss

Head of the Automotive & Industrial business group, graduated in chemical engineering, academic title: Dr.-Ing.



Power semiconductor ::: one of the many products in the Automotive & Industrial portfolio

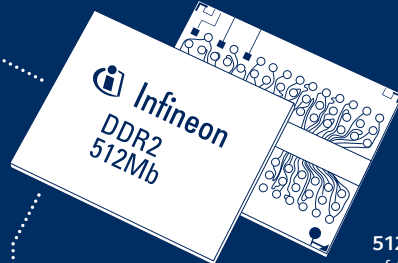
Product innovations

- ::: TriCore-AUDO-NG family, cutting-edge technology: its architecture enables microcontrollers to achieve particularly high performance, with the best real-time response on the market. This instant response makes the chips highly suitable for motor and safety management tasks in vehicles.
- ::: TriCore-2 architecture optimized for industrial applications: the market research institute In-Stat/MDR declared this very low-power semiconductor solution to be the "Best Low-Power Embedded Processor of 2003".
- ::: SPT6 Technology combines the advantages of CMOS with bipolar technology: the combined technology is used in high performance semiconductors. It means fewer components are required and high voltages can be managed with very little power loss.
- ::: Tire-pressure sensors prevent accidents: pressure sensors in the tires notify the driver in good time of any pressure loss and can thus help to prevent an accident resulting from tire damage. The sensors are designed to have very low power consumption and are incorporated into the tire complete with battery.

Memory Products

Thomas Seifert

Head of the Memory Products business group, graduated in business administration, academic title: Dipl.-Kfm., MA in economics



512 Megabit DDR2 SDRAM, memory component ::: one of the many products in the Memory Products portfolio

Product innovations

- ::: Next technology generation presented: first functional samples in 90-nanometer technology are available. The 90-nanometer volume production will begin next year with 512 megabit DDR memory chips.
- ::: Standard DRAM memory with DDR2 interface to come: market launch was in July 2004 for PCs and servers. Next year DDR2 will replace the current DDR generation as a main volume product.
- ::: New memory modules developed: with the micro DIMM, an even smaller memory module for sub-notebooks has been presented. Together with the Wireline Communications business group, a buffer memory for high-speed data transport has been developed, which is to be used in the next generation server modules: the so-called fully buffered DIMMs.
- ::: Specialty memories for 3D graphics cards available: the 500 megahertz GDDR3 graphics memories support highly sophisticated graphics applications.
- ::: DRAMs optimized to run on low power consumption: the 256 megabit Mobile-RAM is now available for 1.8 volt supply voltage and is targeted at smart phones. The 32 megabit CellularRAM replaces expensive SRAMs in mobile phones.
- ::: Introduction of first flash components: at the beginning of 2004, Infineon Technologies Flash, the joint venture with Saifun, Israel, stepped into the market of flash memories with a 512 megabit chip. The flash components can be integrated into USB sticks and flash cards of format secure digital (SD) cards as well as the MultiMediaCard.